

Title (en)

ABRASIVE PAD AND GLASS SUBSTRATE ABRADING METHOD

Title (de)

SCHLEIFKISSEN UND SCHLEIFVERFAHREN FÜR GLASSUBSTRAT

Title (fr)

PATIN ABRASIF ET PROCÉDÉ D'ABRASION DE SUBSTRAT DE VERRE

Publication

EP 3120379 A4 20171101 (EN)

Application

EP 15764427 A 20150317

Priority

- JP 2014056538 A 20140319
- US 2015020859 W 20150317

Abstract (en)

[origin: WO2015142774A1] Problem: To provide an abrasive pad and abrading method using same that are capable of extending the life of the abrasive pad when applied to abrading the surface of glass substrates, and that can ensure abrading capability that is appropriate for abrading the surface of glass substrates. Resolution Means: An abrasive pad used for abrading the surface of a glass substrate, that includes a base material layer, and an abrasive layer provided on one side of the base material layer, the abrasive layer including a plurality of pillar shaped abrading portions arranged separated from each other on the base material layer, the abrading portions being made from abrasive material that includes polishing abrasive particles, a filler, and a binder resin, the polishing abrasive particles including abrasive particles and a glass matrix, and the filler including a first filler that fractures or drops out when the surface is being abraded, forming approximately spherical crown shaped recesses in the top face of the abrading portions.

IPC 8 full level

H01L 21/304 (2006.01); **B24D 3/32** (2006.01); **B24D 3/34** (2006.01); **B24D 18/00** (2006.01)

CPC (source: EP KR US)

B24B 7/17 (2013.01 - EP US); **B24B 7/228** (2013.01 - EP US); **B24B 7/24** (2013.01 - EP KR US); **B24B 37/08** (2013.01 - EP US); **B24B 37/105** (2013.01 - EP US); **B24B 37/245** (2013.01 - EP KR US); **B24B 37/26** (2013.01 - EP KR US); **H01L 21/304** (2013.01 - KR); **H01L 21/30625** (2013.01 - KR); **B24D 2203/00** (2013.01 - EP US)

Citation (search report)

- [X] EP 1094918 A1 20010502 - MINNESOTA MINING & MFG [US]
- [A] WO 2012138705 A2 20121011 - UNIVERSAL PHOTONICS INC [US], et al
- [A] WO 2011058969 A1 20110519 - SHOWA DENKO KK [JP], et al
- [A] US 5078753 A 19920107 - BROBERG DAVID E [US], et al
- See references of WO 2015142774A1

Designated contracting state (EPC)

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DOCDB simple family (publication)

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DOCDB simple family (application)

US 2015020859 W 20150317; CN 201580014499 A 20150317; EP 15764427 A 20150317; JP 2014056538 A 20140319; KR 20167028467 A 20150317; US 201515123444 A 20150317